SELF TESTING METHOD FOR INTEGRATED CIRCUIT DEVICE

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Abstract

PROBLEM TO BE SOLVED: To shorten a wafer test time.
SOLUTION: In order to test an integrated circuit device (chip) having a nonvolatile semiconductor storage device inside, peripheral circuits in the chip to be tested are tested by placing a test circuit 4 in operation with the electric power, generated by an ultraviolet-ray power generating device 3 in a process the ultraviolet-ray power generating device 3, and test circuit 4 are formed on the wafer 1 where chips 2 to be tested are formed and irradiation with ultraviolet rays is performed for the initialization of the nonvolatile semiconductor storage device.